

METHOD AND APPARATUS FOR CUTTING PROTECTIVE TAPE

ABSTRACT OF THE DISCLOSURE

The present invention provides a method of moving a cutter blade along a circumferential edge of a semiconductor wafer, thereby cutting a protective tape joined to a surface of the semiconductor wafer with a pattern
5 formed thereon for protecting the pattern before the semiconductor is processed. The cutter blade moves in the state where a side face thereof is brought into contact with the circumferential edge of the semiconductor wafer, thereby cutting the protective tape joined to the surface of the semiconductor wafer.

(Fig. 5)